



Material Content Data Sheet



Sales Product Name		BSZ100N03LS G		Issued		29. August 2013		
MA#		MA000896766						
Package		PG-TSDSON-8-21		Weight*		37.68 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.709	1.88	1.88	18814	18814
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		63	
	non noble metal	zinc	7440-66-6	0.010	0.03		253	
	non noble metal	iron	7439-89-6	0.190	0.51		5055	
wire	non noble metal	copper	7440-50-8	7.733	20.52	21.07	205242	210613
	noble metal	gold	7440-57-5	0.212	0.56	0.56	5628	5628
encapsulation	organic material	carbon black	1333-86-4	0.038	0.10		1017	
	plastics	epoxy resin	-	1.974	5.24		52387	
	inorganic material	silicondioxide	60676-86-0	17.150	45.52	50.86	455209	508613
leadfinish	non noble metal	tin	7440-31-5	0.387	1.03	1.03	10276	10276
plating	noble metal	silver	7440-22-4	0.963	2.55	2.55	25549	25549
solder	non noble metal	tin	7440-31-5	0.051	0.14		1363	
	non noble metal	lead	7439-92-1	0.976	2.59	2.73	25902	27265
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		29	
	non noble metal	zinc	7440-66-6	0.004	0.01		118	
	non noble metal	iron	7439-89-6	0.089	0.24		2360	
	non noble metal	copper	7440-50-8	3.610	9.58	9.83	95828	98335
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		28	
	non noble metal	zinc	7440-66-6	0.004	0.01		114	
	non noble metal	iron	7439-89-6	0.086	0.23		2278	
	non noble metal	copper	7440-50-8	3.484	9.25	9.49	92487	94907
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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